



Material Content Data Sheet



Halogen-Free

Sales Product Name	IPD50R800CE	Issued	25. June 2021
MA#	MA005558091		
Package	PG-TO252-3-344	Weight*	322.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.092	0.65	0.65	6486	6486
leadframe	inorganic material	phosphorus	7723-14-0	0.053	0.02		165	
	non noble metal	iron	7439-89-6	0.177	0.05		549	
	non noble metal	copper	7440-50-8	176.899	54.86	54.93	548561	549275
wire	non noble metal	aluminium	7429-90-5	0.526	0.16	0.16	1630	1630
encapsulation	organic material	carbon black	1333-86-4	0.683	0.21		2119	
	plastics	epoxy resin	-	18.450	5.72		57213	
	inorganic material	silicondioxide	60676-86-0	117.532	36.45	42.38	364466	423798
leadfinish	non noble metal	tin	7440-31-5	3.834	1.19	1.19	11888	11888
solder	non noble metal	tin	7440-31-5	0.045	0.01		138	
	noble metal	silver	7440-22-4	0.056	0.02		173	
	non noble metal	lead	7439-92-1	2.132	0.66	0.69	6612	6923
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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